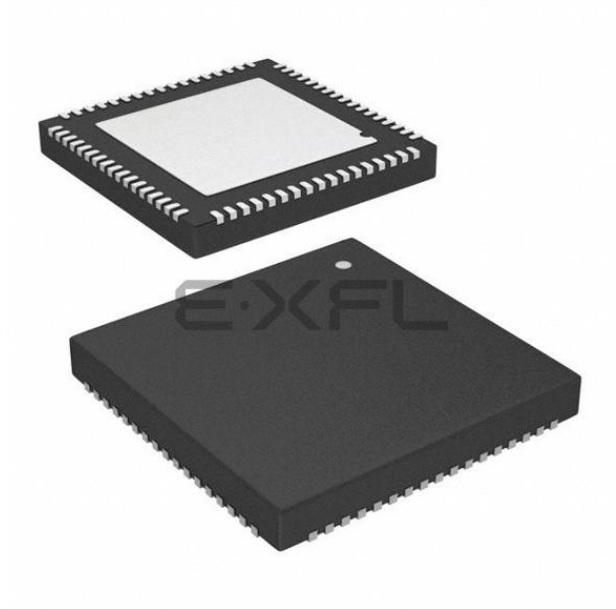
Infineon Technologies - CY8C3244LTI-130 Datasheet



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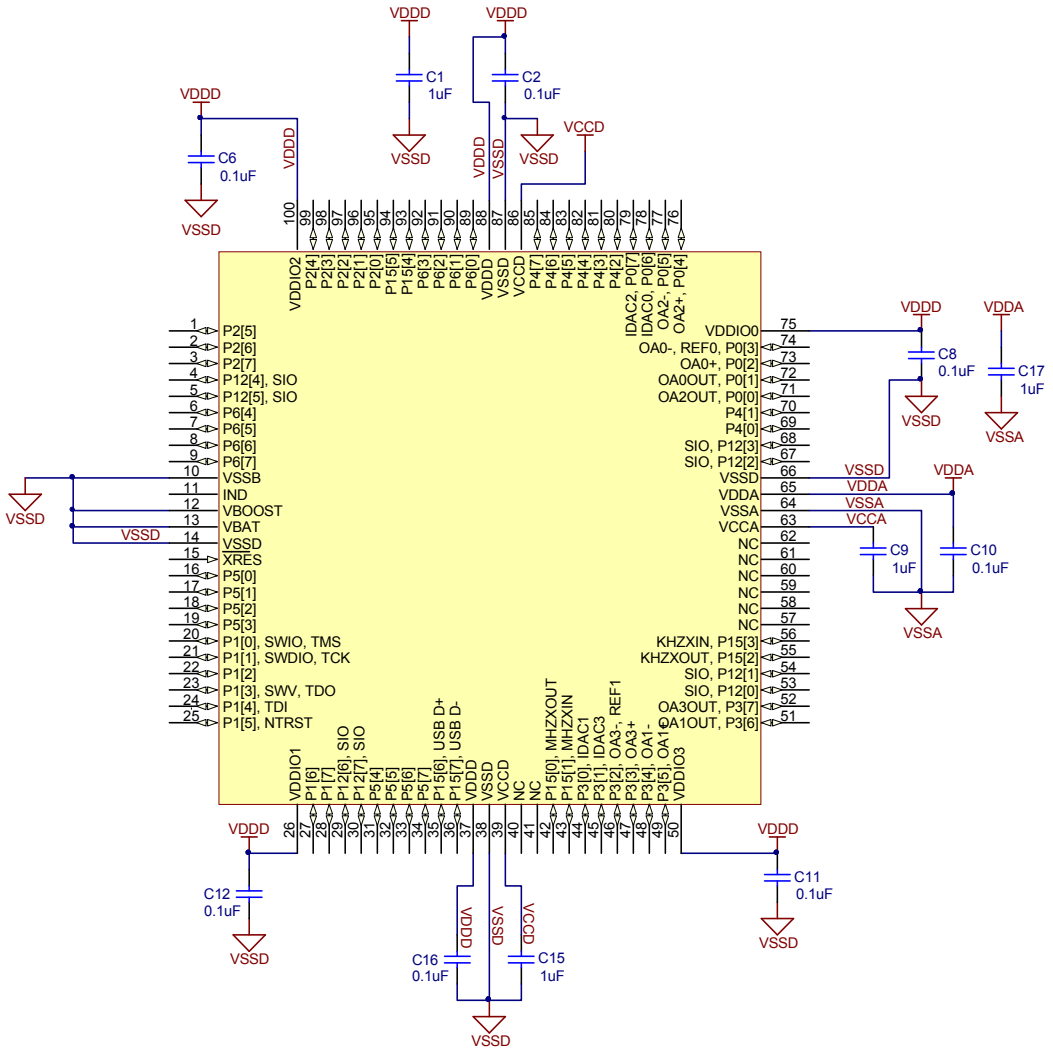
"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	8051
Core Size	8-Bit
Speed	50MHz
Connectivity	EBI/EMI, I²C, LINbus, SPI, UART/USART
Peripherals	CapSense, DMA, POR, PWM, WDT
Number of I/O	38
Program Memory Size	16KB (16K x 8)
Program Memory Type	FLASH
EEPROM Size	512 x 8
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	1.71V ~ 5.5V
Data Converters	A/D 16x12b; D/A 1x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	68-VFQFN Exposed Pad
Supplier Device Package	68-QFN (8x8)
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/cy8c3244lti-130

Figure 2-7. Example Schematic for 100-pin TQFP Part with Power Connections



Note The two VCCD pins must be connected together with as short a trace as possible. A trace under the device is recommended, as shown in Figure 2-8 on page 12.

For more information on pad layout, refer to http://www.cypress.com/cad-resources/psoc-3-cad-libraries.

4.3.1.3 Data Transfer Instructions

The data transfer instructions are of three types: the core RAM, xdata RAM, and the lookup tables. The core RAM transfer includes transfer between any two core RAM locations or SFRs. These instructions can use direct, indirect, register, and immediate addressing. The xdata RAM transfer includes only the transfer between the accumulator and the xdata RAM location. It can use only indirect addressing. The lookup tables involve nothing but the read of program memory using the Indexed addressing mode. Table 4-3 lists the various data transfer instructions available.

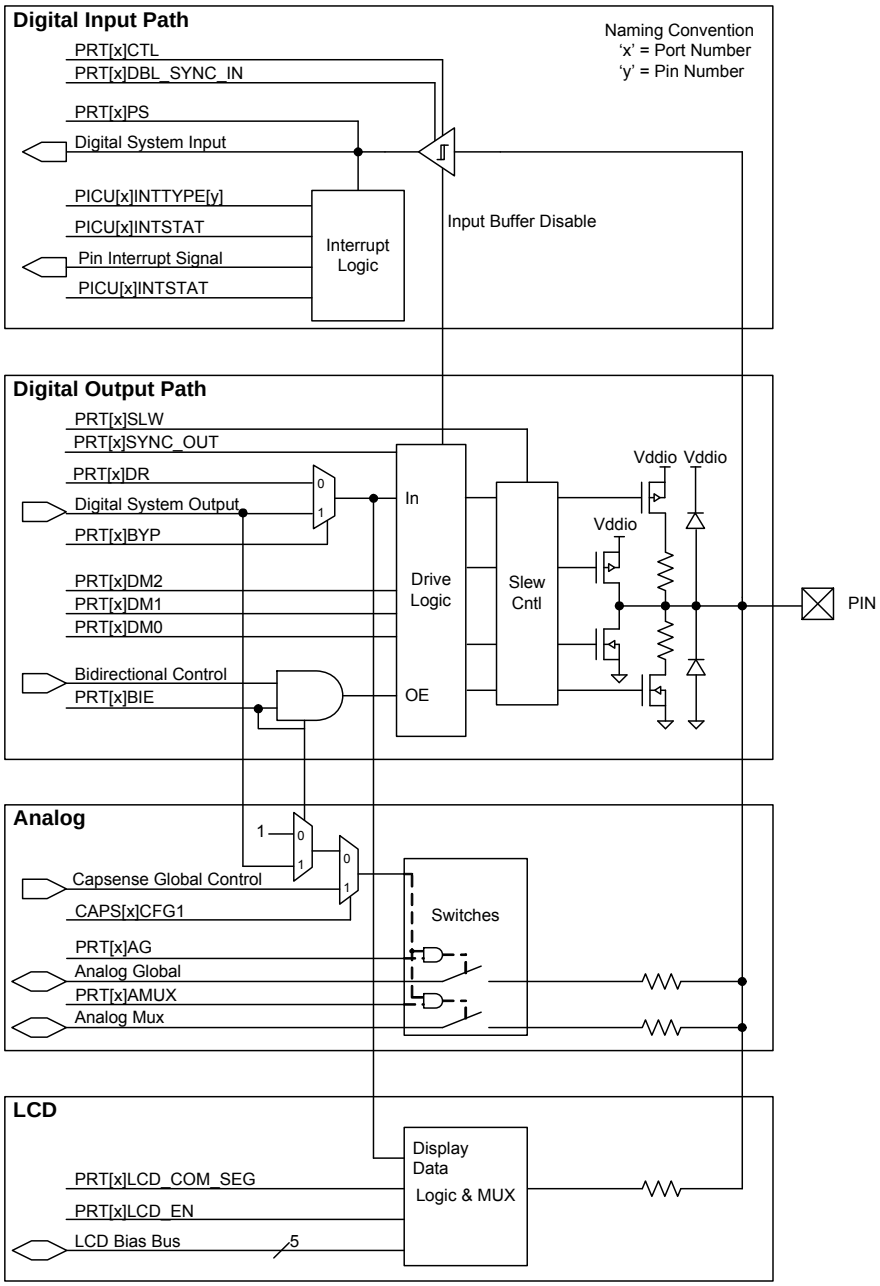
4.3.1.4 Boolean Instructions

The 8051 core has a separate bit-addressable memory location. It has 128 bits of bit addressable RAM and a set of SFRs that are bit addressable. The instruction set includes the whole menu of bit operations such as move, set, clear, toggle, OR, and AND instructions and the conditional jump instructions. Table 4-4 on page 17Table 4-4 lists the available Boolean instructions.

Table 4-3. Data Transfer Instructions

Mnemonic	Description	Bytes	Cycles
MOV A,Rn	Move register to accumulator	1	1
MOV A,Direct	Move direct byte to accumulator	2	2
MOV A,@Ri	Move indirect RAM to accumulator	1	2
MOV A,#data	Move immediate data to accumulator	2	2
MOV Rn,A	Move accumulator to register	1	1
MOV Rn,Direct	Move direct byte to register	2	3
MOV Rn, #data	Move immediate data to register	2	2
MOV Direct, A	Move accumulator to direct byte	2	2
MOV Direct, Rn	Move register to direct byte	2	2
MOV Direct, Direct	Move direct byte to direct byte	3	3
MOV Direct, @Ri	Move indirect RAM to direct byte	2	3
MOV Direct, #data	Move immediate data to direct byte	3	3
MOV @Ri, A	Move accumulator to indirect RAM	1	2
MOV @Ri, Direct	Move direct byte to indirect RAM	2	3
MOV @Ri, #data	Move immediate data to indirect RAM	2	2
MOV DPTR, #data16	Load data pointer with 16-bit constant	3	3
MOVC A, @A+DPTR	Move code byte relative to DPTR to accumulator	1	5
MOVC A, @A + PC	Move code byte relative to PC to accumulator	1	4
MOVX A,@Ri	Move external RAM (8-bit) to accumulator	1	4
MOVX A, @DPTR	Move external RAM (16-bit) to accumulator	1	3
MOVX @Ri, A	Move accumulator to external RAM (8-bit)	1	5
MOVX @DPTR, A	Move accumulator to external RAM (16-bit)	1	4
PUSH Direct	Push direct byte onto stack	2	3
POP Direct	Pop direct byte from stack	2	2
XCH A, Rn	Exchange register with accumulator	1	2
XCH A, Direct	Exchange direct byte with accumulator	2	3
XCH A, @Ri	Exchange indirect RAM with accumulator	1	3
XCHD A, @Ri	Exchange low order indirect digit RAM with accumulator	1	3

Figure 6-9. GPIO Block Diagram



7. Digital Subsystem

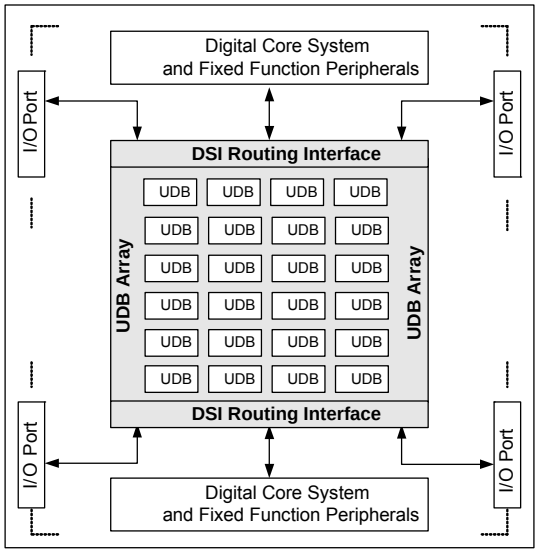
The digital programmable system creates application specific combinations of both standard and advanced digital peripherals and custom logic functions. These peripherals and logic are then interconnected to each other and to any pin on the device, providing a high level of design flexibility and IP security.

The features of the digital programmable system are outlined here to provide an overview of capabilities and architecture. You do not need to interact directly with the programmable digital system at the hardware and register level. PSoC Creator provides a high level schematic capture graphical interface to automatically place and route resources similar to PLDs.

The main components of the digital programmable system are:

- Universal Digital Blocks (UDB) – These form the core functionality of the digital programmable system. UDBs are a collection of uncommitted logic (PLD) and structural logic (Datapath) optimized to create all common embedded peripherals and customized functionality that are application or design specific.
- Universal Digital Block Array – UDB blocks are arrayed within a matrix of programmable interconnect. The UDB array structure is homogeneous and allows for flexible mapping of digital functions onto the array. The array supports extensive and flexible routing interconnects between UDBs and the Digital System Interconnect.
- Digital System Interconnect (DSI) – Digital signals from Universal Digital Blocks (UDBs), fixed function peripherals, I/O pins, interrupts, DMA, and other system core signals are attached to the Digital System Interconnect to implement full featured device connectivity. The DSI allows any digital function to any pin or other feature routability when used with the Universal Digital Block Array.

Figure 7-1. CY8C32 Digital Programmable Architecture



7.1 Example Peripherals

The flexibility of the CY8C32 family's Universal Digital Blocks (UDBs) and Analog Blocks allow the user to create a wide range of components (peripherals). The most common peripherals were built and characterized by Cypress and are shown in the PSoC Creator component catalog, however, users may also create their own custom components using PSoC Creator. Using PSoC Creator, users may also create their own components for reuse within their organization, for example sensor interfaces, proprietary algorithms, and display interfaces.

The number of components available through PSoC Creator is too numerous to list in the datasheet, and the list is always growing. An example of a component available for use in CY8C32 family, but, not explicitly called out in this datasheet is the UART component.

7.1.1 Example Digital Components

The following is a sample of the digital components available in PSoC Creator for the CY8C32 family. The exact amount of hardware resources (UDBs, routing, RAM, flash) used by a component varies with the features selected in PSoC Creator for the component.

- Communications
  - I^2C
  - UART
  - SPI
- Functions
  - EMIF
  - PWMs
  - Timers
  - Counters
- Logic
  - NOT
  - OR
  - XOR
  - AND

7.1.2 Example Analog Components

The following is a sample of the analog components available in PSoC Creator for the CY8C32 family. The exact amount of hardware resources (routing, RAM, flash) used by a component varies with the features selected in PSoC Creator for the component.

- ADC
  - Delta-sigma
- DACs
  - Current
  - Voltage
  - PWM
- Comparators

7.1.3 Example System Function Components

The following is a sample of the system function components available in PSoC Creator for the CY8C32 family. The exact amount of hardware resources (UDBs, routing, RAM, flash) used by a component varies with the features selected in PSoC Creator for the component.

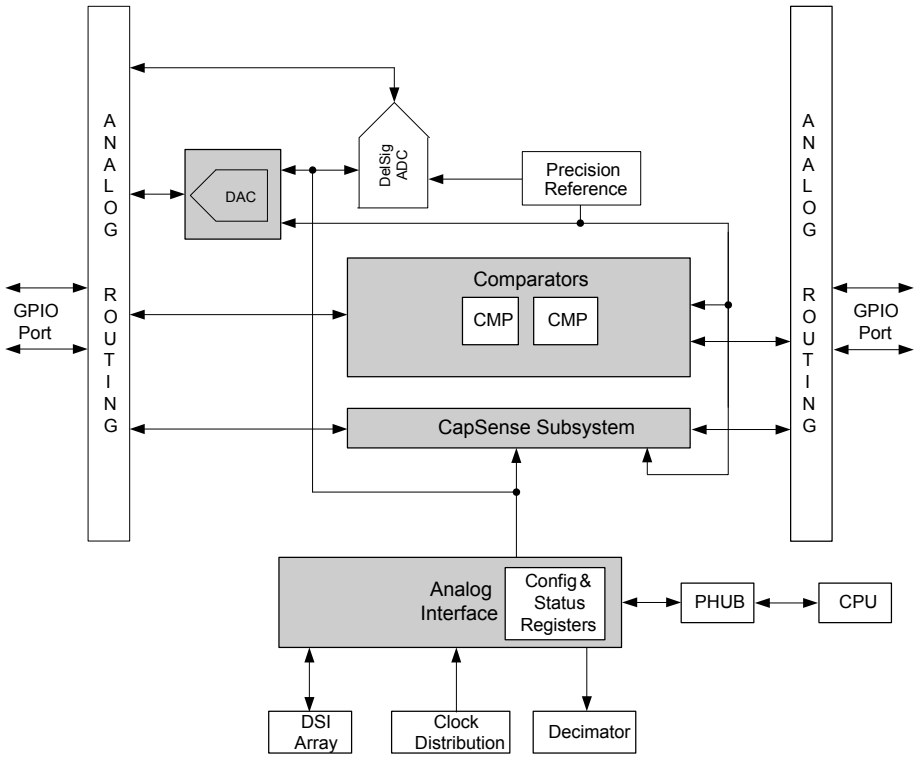
- CapSense
- LCD Drive
- LCD Control

8. Analog Subsystem

The analog programmable system creates application specific combinations of both standard and advanced analog signal processing blocks. These blocks are then interconnected to each other and also to any pin on the device, providing a high level of design flexibility and IP security. The features of the analog subsystem are outlined here to provide an overview of capabilities and architecture.

- Flexible, configurable analog routing architecture provided by analog globals, analog mux bus, and analog local buses.
- High resolution delta-sigma ADC.
- One 8-bit DAC that provides either voltage or current output.
- Two comparators with optional connection to configurable LUT outputs.
- CapSense subsystem to enable capacitive touch sensing.
- Precision reference for generating an accurate analog voltage for internal analog blocks.

Figure 8-1. Analog Subsystem Block Diagram



The PSoC Creator software program provides a user friendly interface to configure the analog connections between the GPIO and various analog resources and connections from one analog resource to another. PSoC Creator also provides component libraries that allow you to configure the various analog blocks to perform application specific functions. The tool also generates API interface libraries that allow you to write firmware that allows the communication between the analog peripheral and CPU/Memory.

8.3.2 LUT

The CY8C32 family of devices contains four LUTs. The LUT is a two input, one output lookup table that is driven by any one or two of the comparators in the chip. The output of any LUT is routed to the digital system interface of the UDB array. From the digital system interface of the UDB array, these signals can be connected to UDBs, DMA controller, I/O, or the interrupt controller.

The LUT control word written to a register sets the logic function on the output. The available LUT functions and the associated control word is shown in Table 8-2.

Table 8-2. LUT Function vs. Program Word and Inputs

Control Word	Output (A and B are LUT inputs)
0000b	**FALSE** (‘0’)
0001b	**A** AND **B**
0010b	**A** AND (NOT **B**)
0011b	A
0100b	(NOT **A**) AND **B**
0101b	B
0110b	**A** XOR **B**
0111b	**A** OR **B**
1000b	**A** NOR **B**
1001b	**A** XNOR **B**
1010b	NOT **B**
1011b	**A** OR (NOT **B**)
1100b	NOT **A**
1101b	(NOT **A**) OR **B**
1110b	**A** NAND **B**
1111b	**TRUE** (‘1’)

8.4 LCD Direct Drive

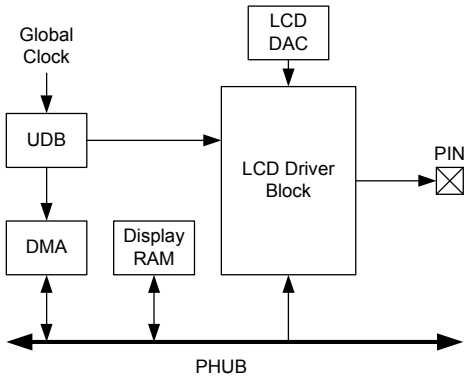
The PSoC Liquid Crystal Display (LCD) driver system is a highly configurable peripheral designed to allow PSoC to directly drive a broad range of LCD glass. All voltages are generated on chip, eliminating the need for external components. With a high multiplex ratio of up to 1/16, the CY8C32 family LCD driver system can drive a maximum of 736 segments. The PSoC LCD driver module was also designed with the conservative power budget of portable devices in mind, enabling different LCD drive modes and power down modes to conserve power.

PSoC Creator provides an LCD segment drive component. The component wizard provides easy and flexible configuration of LCD resources. You can specify pins for segments and commons along with other options. The software configures the device to meet the required specifications. This is possible because of the programmability inherent to PSoC devices.

Key features of the PSoC LCD segment system are:

- LCD panel direct driving
- Type A (standard) and Type B (low-power) waveform support
- Wide operating voltage range support (2 V to 5 V) for LCD panels
- Static, 1/2, 1/3, 1/4, 1/5 bias voltage levels
- Internal bias voltage generation through internal resistor ladder
- Up to 62 total common and segment outputs
- Up to 1/16 multiplex for a maximum of 16 backplane/common outputs
- Up to 62 front plane/segment outputs for direct drive
- Drives up to 736 total segments (16 backplane × 46 front plane)
- Up to 64 levels of software controlled contrast
- Ability to move display data from memory buffer to LCD driver through DMA (without CPU intervention)
- Adjustable LCD refresh rate from 10 Hz to 150 Hz
- Ability to invert LCD display for negative image
- Three LCD driver drive modes, allowing power optimization

Figure 8-6. LCD System



8.4.1 LCD Segment Pin Driver

Each GPIO pin contains an LCD driver circuit. The LCD driver buffers the appropriate output of the LCD DAC to directly drive the glass of the LCD. A register setting determines whether the pin is a common or segment. The pin’s LCD driver then selects one of the six bias voltages to drive the I/O pin, as appropriate for the display data.

8.4.2 Display Data Flow

The LCD segment driver system reads display data and generates the proper output voltages to the LCD glass to produce the desired image. Display data resides in a memory buffer in the system SRAM. Each time you need to change the common and segment driver voltages, the next set of pixel data moves from the memory buffer into the Port Data Registers via DMA.

8.4.3 UDB and LCD Segment Control

A UDB is configured to generate the global LCD control signals and clocking. This set of signals is routed to each LCD pin driver through a set of dedicated LCD global routing channels. In addition to generating the global LCD control signals, the UDB also produces a DMA request to initiate the transfer of the next frame of LCD data.

Figure 11-1. Active Mode Current vs F_{CPU}, V_{DD} = 3.3 V, Temperature = 25 °C

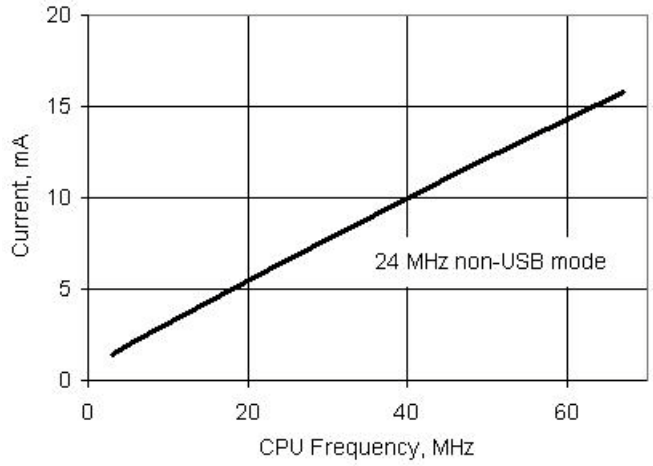


Figure 11-2. Active Mode Current vs Temperature and F_{CPU}, V_{DD} = 3.3 V

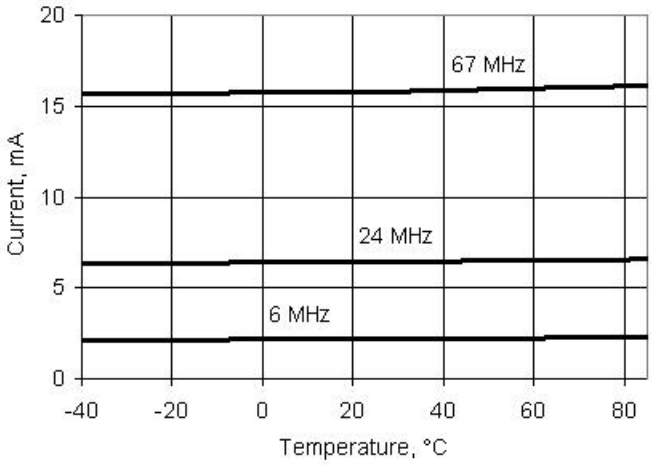
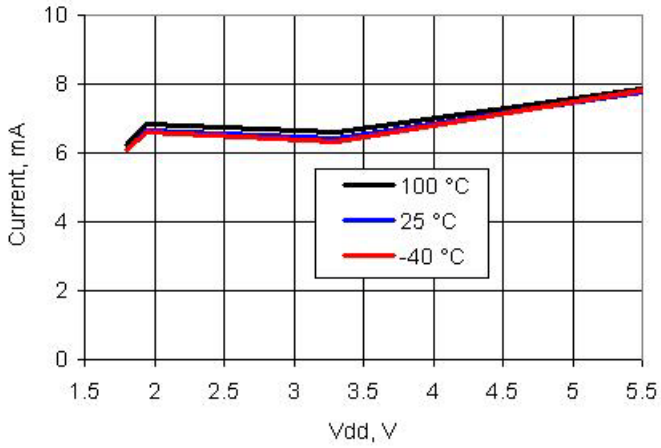


Figure 11-3. Active Mode Current vs V_{DD} and Temperature, F_{CPU} = 24 MHz



Notes
25. If V_{CCD} and V_{CCA} are externally regulated, the voltage difference between V_{CCD} and V_{CCA} must be less than 50 mV.
26. Sleep timer generates periodic interrupts to wake up the CPU. This specification applies only to those times that the CPU is off.
27. Externally regulated mode.
28. Based on device characterization (not production tested).
29. Based on device characterization (not production tested). USBIO pins tied to ground (V_{SSD}).

Figure 11-22. USBIO Output High Voltage and Current, GPIO Mode

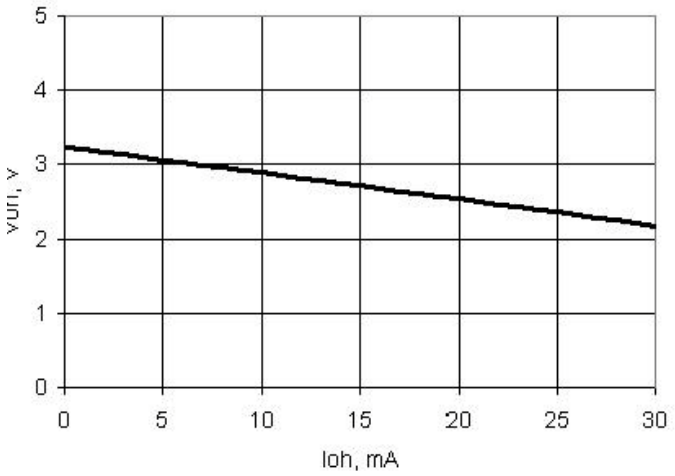


Figure 11-23. USBIO Output Low Voltage and Current, GPIO Mode

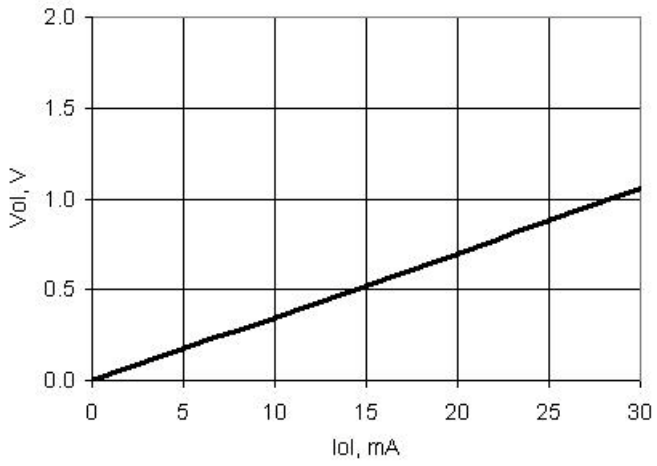


Table 11-15. USBIO AC Specifications

Parameter	Description	Conditions	Min	Typ	Max	Units
Tdrate	Full-speed data rate average bit rate		12 – 0.25%	12	12 + 0.25%	MHz
Tjr1	Receiver data jitter tolerance to next transition		–8	–	8	ns
Tjr2	Receiver data jitter tolerance to pair transition		–5	–	5	ns
Tdj1	Driver differential jitter to next transition		–3.5	–	3.5	ns
Tdj2	Driver differential jitter to pair transition		–4	–	4	ns
Tfdeop	Source jitter for differential transition to SE0 transition		–2	–	5	ns
Tfeopt	Source SE0 interval of EOP		160	–	175	ns
Tfeopr	Receiver SE0 interval of EOP		82	–	–	ns
Tfst	Width of SE0 interval during differential transition		–	–	14	ns
Fgpio_out	GPIO mode output operating frequency	3 V ≤ V_{DDD} ≤ 5.5 V	–	–	20	MHz
		V_{DDD} = 1.71 V	–	–	6	MHz
Tr_gpio	Rise time, GPIO mode, 10%/90% V_{DDD}	V_{DDD} > 3 V, 25 pF load	–	–	12	ns
		V_{DDD} = 1.71 V, 25 pF load	–	–	40	ns
Tf_gpio	Fall time, GPIO mode, 90%/10% V_{DDD}	V_{DDD} > 3 V, 25 pF load	–	–	12	ns
		V_{DDD} = 1.71 V, 25 pF load	–	–	40	ns

Figure 11-24. USBIO Output Rise and Fall Times, GPIO Mode,

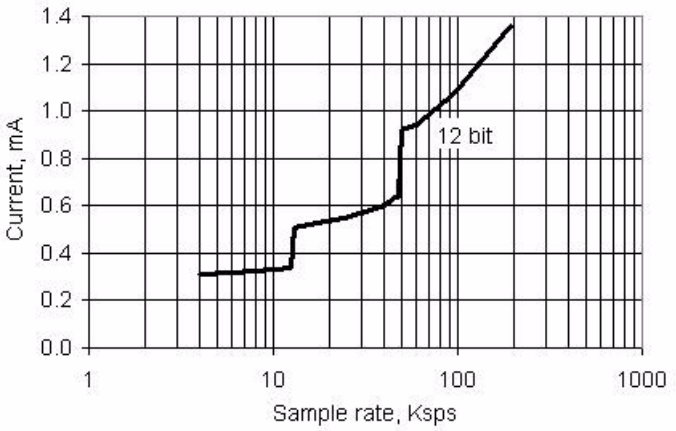
Table 11-20. Delta-sigma ADC AC Specifications

Parameter	Description	Conditions	Min	Typ	Max	Units
	Startup time		–	–	4	Samples
THD	Total harmonic distortion[48]	Buffer gain = 1, 12-bit, Range = ±1.024 V	–	–	0.0032	%
12-Bit Resolution Mode						
SR12	Sample rate, continuous, high power[48]	Range = ±1.024 V, unbuffered	4	–	192	ksps
BW12	Input bandwidth at max sample rate[48]	Range = ±1.024 V, unbuffered	–	44	–	kHz
SINAD12int	Signal to noise ratio, 12-bit, internal reference[48]	Range = ±1.024 V, unbuffered	66	–	–	dB
8-Bit Resolution Mode						
SR8	Sample rate, continuous, high power[48]	Range = ±1.024 V, unbuffered	8	–	384	ksps
BW8	Input bandwidth at max sample rate[48]	Range = ±1.024 V, unbuffered	–	88	–	kHz
SINAD8int	Signal to noise ratio, 8-bit, internal reference[48]	Range = ±1.024 V, unbuffered	43	–	–	dB

Table 11-21. Delta-sigma ADC Sample Rates, Range = ±1.024 V

Resolution, Bits	Continuous		Multi-Sample	
	Min	Max	Min	Max
8	8000	384000	1911	91701
9	6400	307200	1543	74024
10	5566	267130	1348	64673
11	4741	227555	1154	55351
12	4000	192000	978	46900

Figure 11-25. Delta-sigma ADC IDD vs sps, Range = ±1.024 V, Continuous Sample Mode, Input Buffer Bypassed



Note
48. Based on device characterization (Not production tested).

11.5.2 Voltage Reference

Table 11-22. Voltage Reference Specifications

See also ADC external reference specifications in Section 11.5.1.

Parameter	Description	Conditions	Min	Typ	Max	Units
V_{REF}	Precision reference voltage	Initial trimming, 25 °C	1.014 (–1%)	1.024	1.034 (+1%)	V

11.5.3 Analog Globals

Table 11-23. Analog Globals Specifications

Parameter	Description	Conditions	Min	Typ	Max	Units
Rppag	Resistance pin-to-pin through P2[4], AGL0, DSM INP, AGL1, P2[5][49]	V_{DDA} = 3 V	–	1472	2200	Ω
Rppmuxbus	Resistance pin-to-pin through P2[3], amuxbusL, P2[4][49]	V_{DDA} = 3 V	–	706	1100	Ω

11.5.4 Comparator

Table 11-24. Comparator DC Specifications

Parameter	Description	Conditions	Min	Typ	Max	Units
V_{OS}	Input offset voltage in fast mode	Factory trim, V_{DDA} > 2.7 V, $V_{IN} \geq 0.5$ V	–		10	mV
	Input offset voltage in slow mode	Factory trim, $V_{IN} \geq 0.5$ V	–		9	mV
	Input offset voltage in fast mode[50]	Custom trim	–	–	4	mV
	Input offset voltage in slow mode[50]	Custom trim	–	–	4	mV
	Input offset voltage in ultra low-power mode	$V_{DDA} \leq 4.6$ V	–	±12	–	mV
V_{HYST}	Hysteresis	Hysteresis enable mode	–	10	32	mV
V_{ICM}	Input common mode voltage	High current / fast mode	V_{SSA}	–	V_{DDA}	V
		Low current / slow mode	V_{SSA}	–	V_{DDA}	V
		Ultra low power mode $V_{DDA} \leq 4.6$ V	V_{SSA}	–	V_{DDA} – 1.15	
CMRR	Common mode rejection ratio		–	50	–	dB
I_{CMP}	High current mode/fast mode[51]		–	–	400	µA
	Low current mode/slow mode[51]		–	–	100	µA
	Ultra low-power mode[51]	$V_{DDA} \leq 4.6$ V	–	6	–	µA

Table 11-25. Comparator AC Specifications

Parameter	Description	Conditions	Min	Typ	Max	Units
Tresp	Response time, high current mode[51]	50 mV overdrive, measured pin-to-pin	–	75	110	ns
	Response time, low current mode[51]	50 mV overdrive, measured pin-to-pin	–	155	200	ns
	Response time, ultra low-power mode[51]	50 mV overdrive, measured pin-to-pin, $V_{DDA} \leq 4.6$ V	–	55	–	µs

Notes
49. The resistance of the analog global and analog mux bus is high if $V_{DDA} \leq 2.7$ V, and the chip is in either sleep or hibernate mode. Use of analog global and analog mux bus under these conditions is not recommended
50. The recommended procedure for using a custom trim value for the on-chip comparators can be found in the TRM.
51. Based on device characterization (Not production tested).

Figure 11-28. IDAC DNL vs Input Code, Range = 255 µA, Source Mode

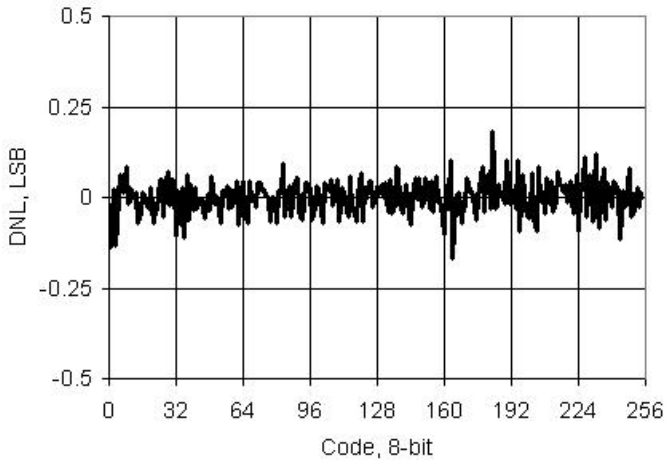


Figure 11-29. IDAC DNL vs Input Code, Range = 255 µA, Sink Mode

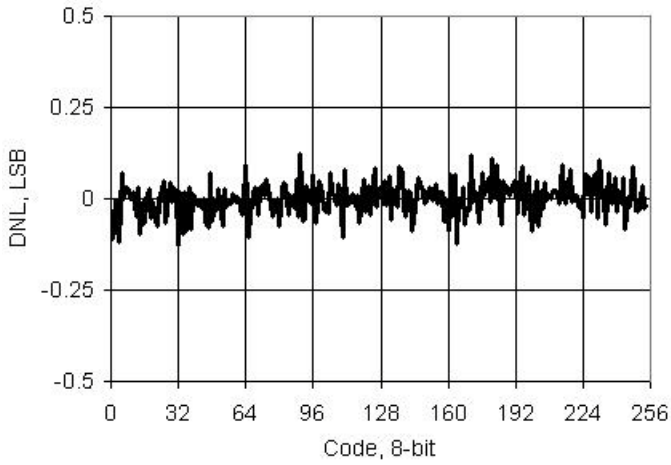


Figure 11-30. IDAC INL vs Temperature, Range = 255 µA, High speed mode

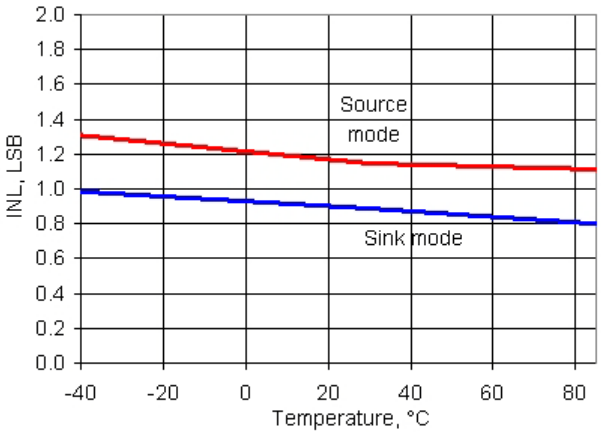


Figure 11-31. IDAC DNL vs Temperature, Range = 255 µA, High speed mode

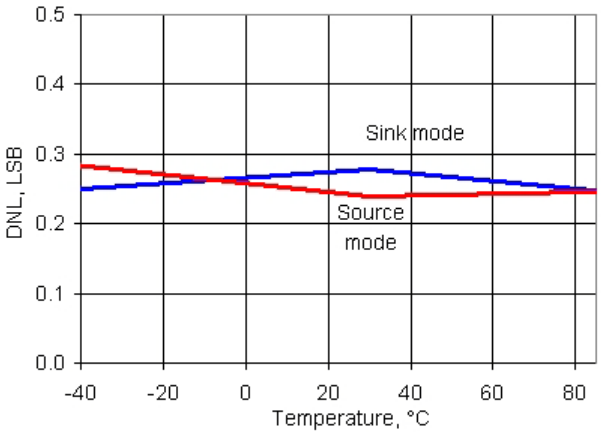


Figure 11-32. IDAC Full Scale Error vs Temperature, Range = 255 µA, Source Mode

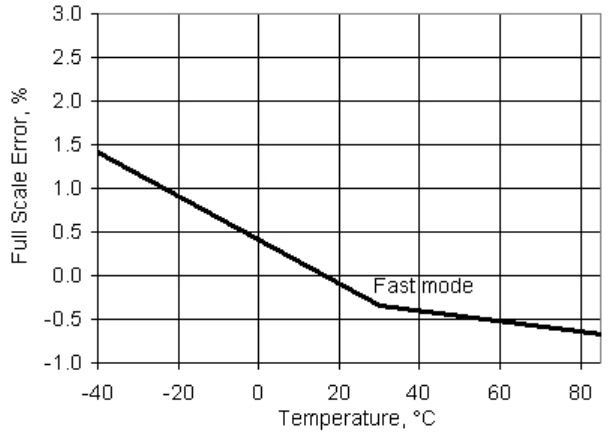


Figure 11-33. IDAC Full Scale Error vs Temperature, Range = 255 µA, Sink Mode

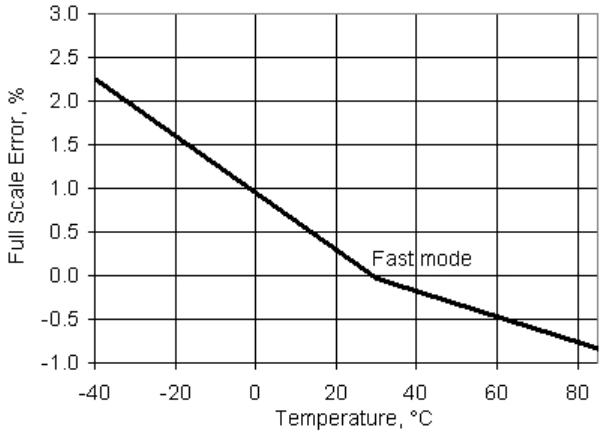


Figure 11-34. IDAC Operating Current vs Temperature, Range = 255 µA, Code = 0, Source Mode

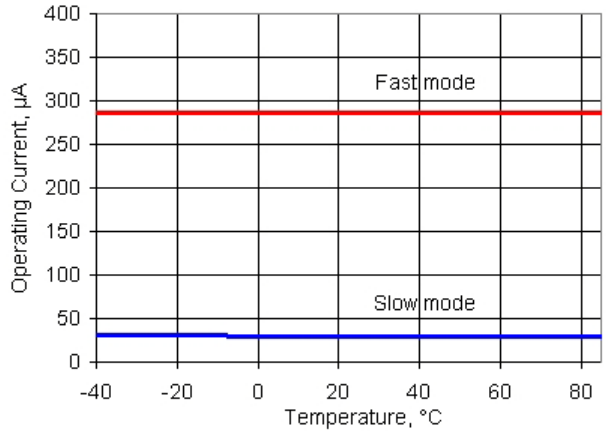


Figure 11-35. IDAC Operating Current vs Temperature, Range = 255 µA, Code = 0, Sink Mode

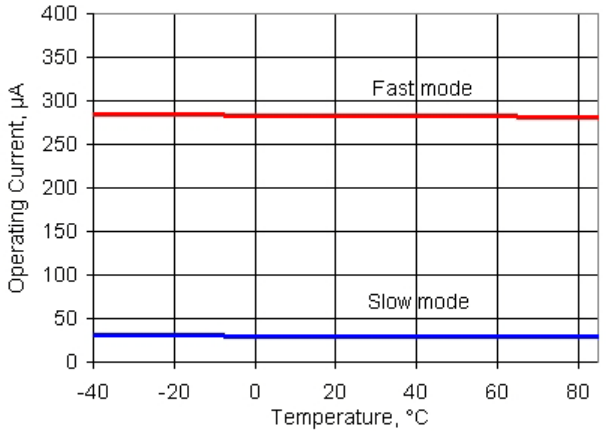


Table 11-27. IDAC AC Specifications

Parameter	Description	Conditions	Min	Typ	Max	Units
F_{DAC}	Update rate		–	–	8	Msps
T_{SETTLE}	Settling time to 0.5 LSB	Range = 31.875 µA or 255 µA, full scale transition, High speed mode, 600 Ω 15-pF load	–	–	125	ns
	Current noise	Range = 255 µA, source mode, High speed mode, V_{DDA} = 5 V, 10 kHz	–	340	–	pA/sqrtHz

Figure 11-36. IDAC Step Response, Codes 0x40 - 0xC0, 255 µA Mode, Source Mode, High speed mode, V_{DDA} = 5 V

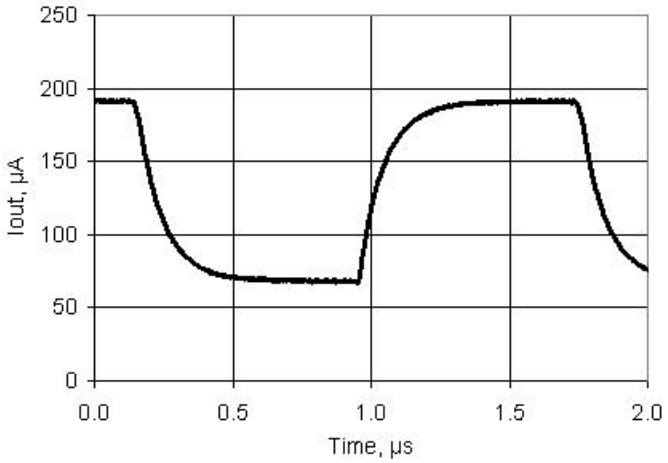


Figure 11-37. IDAC Glitch Response, Codes 0x7F - 0x80, 255 µA Mode, Source Mode, High speed mode, V_{DDA} = 5 V

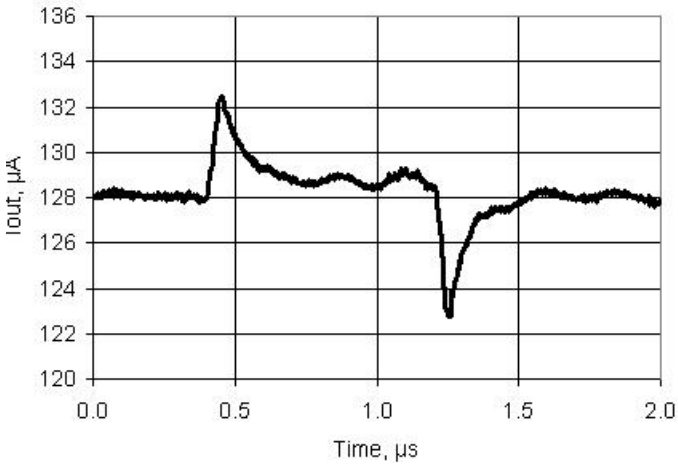


Figure 11-38. IDAC PSRR vs Frequency

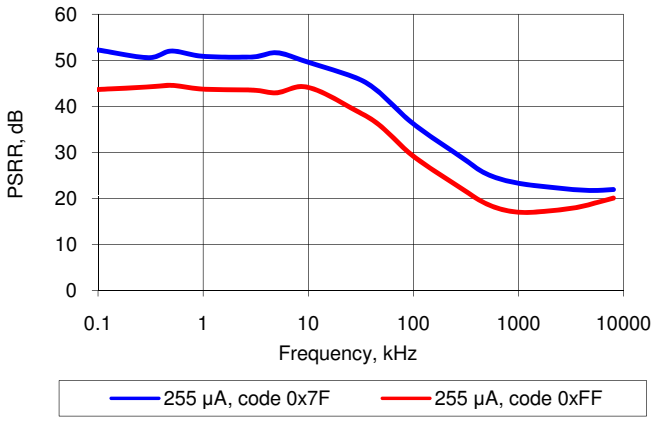
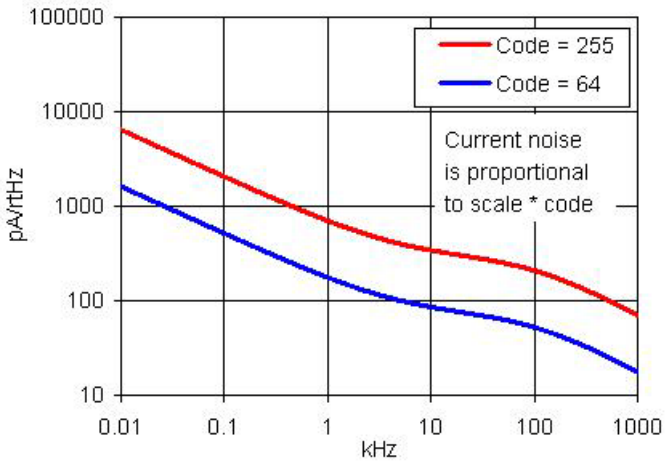


Figure 11-39. IDAC Current Noise, 255 µA Mode, Source Mode, High speed mode, V_{DDA} = 5 V



11.5.6 Voltage Digital to Analog Converter (VDAC)

See the VDAC component datasheet in PSoC Creator for full electrical specifications and APIs.

Unless otherwise specified, all charts and graphs show typical values.

Table 11-28. VDAC DC Specifications

Parameter	Description	Conditions	Min	Typ	Max	Units
	Resolution		–	8	–	bits
INL1	Integral nonlinearity	1 V scale	–	±2.1	±2.5	LSB
INL4	Integral nonlinearity[52]	4 V scale	–	±2.1	±2.5	LSB
DNL1	Differential nonlinearity	1 V scale	–	±0.3	±1	LSB
DNL4	Differential nonlinearity[52]	4 V scale	–	±0.3	±1	LSB
Rout	Output resistance	1 V scale	–	4	–	kΩ
		4 V scale	–	16	–	kΩ
V_{OUT}	Output voltage range, code = 255	1 V scale	–	1.02	–	V
		4 V scale, V_{DDA} = 5 V	–	4.08	–	V
	Monotonicity		–	–	Yes	–
V_{OS}	Zero scale error		–	0	±0.9	LSB
Eg	Gain error	1 V scale	–	–	±2.5	%
		4 V scale	–	–	±2.5	%
TC_Eg	Temperature coefficient, gain error	1 V scale	–	–	0.03	%FSR / °C
		4 V scale	–	–	0.03	%FSR / °C
I_{DD}	Operating current	Low speed mode	–	–	100	µA
		High speed mode	–	–	500	µA

Figure 11-40. VDAC INL vs Input Code, 1 V Mode

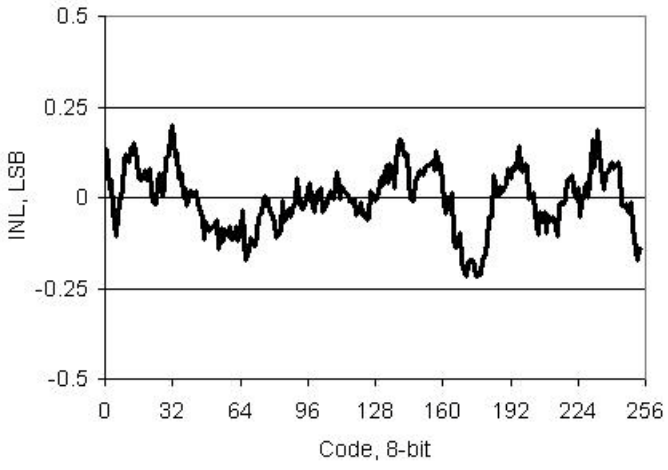
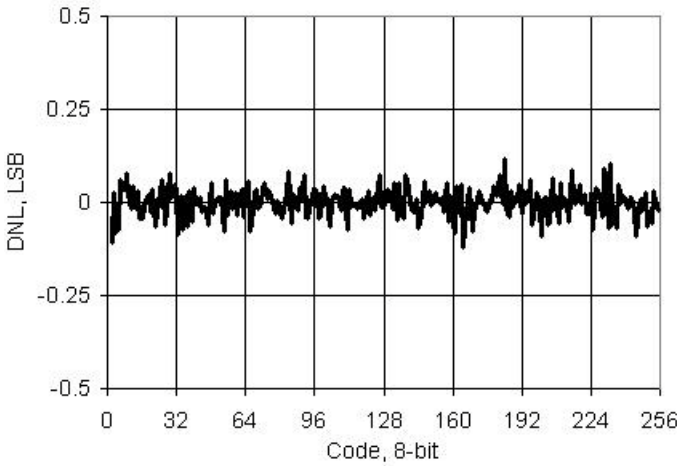


Figure 11-41. VDAC DNL vs Input Code, 1 V Mode



Note
52. Based on device characterization (Not production tested).

Figure 11-42. VDAC INL vs Temperature, 1 V Mode

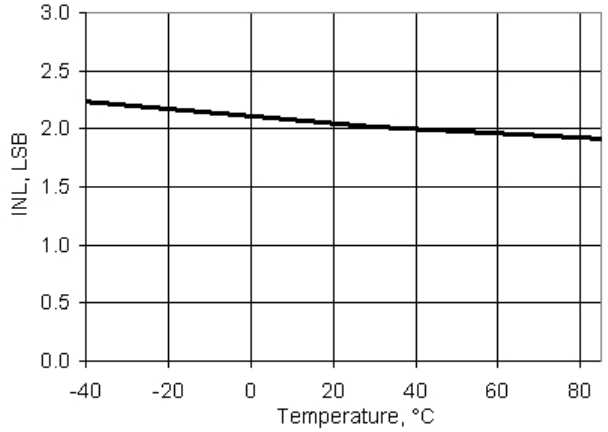


Figure 11-43. VDAC DNL vs Temperature, 1 V Mode

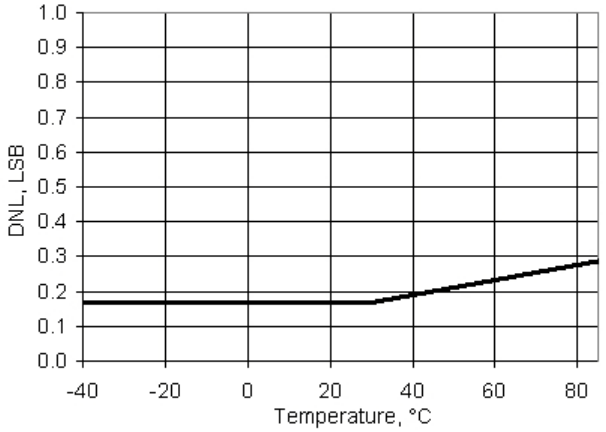


Figure 11-44. VDAC Full Scale Error vs Temperature, 1 V Mode

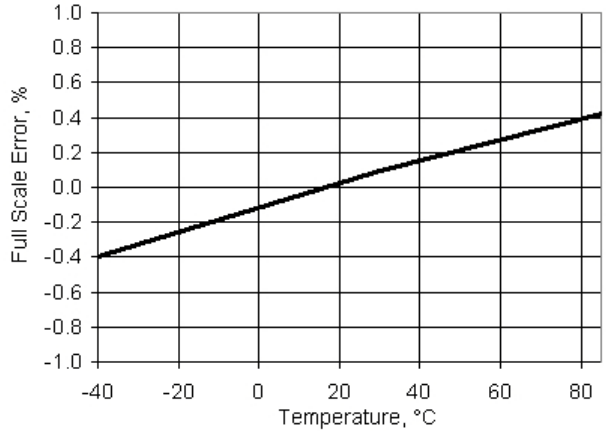


Figure 11-45. VDAC Full Scale Error vs Temperature, 4 V Mode

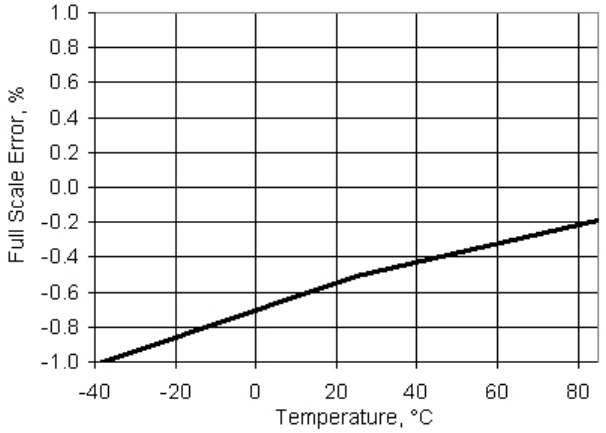


Figure 11-46. VDAC Operating Current vs Temperature, 1V Mode, Low speed mode

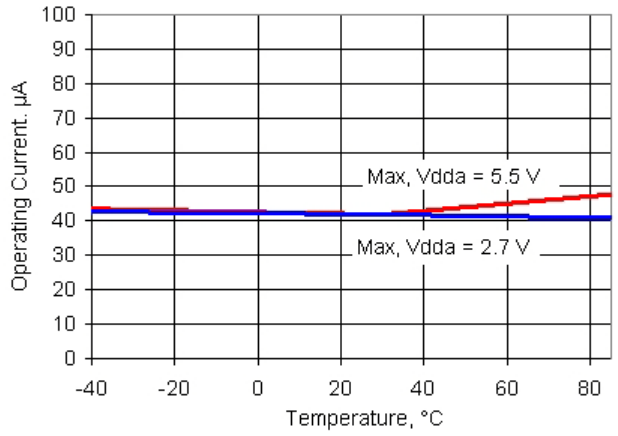
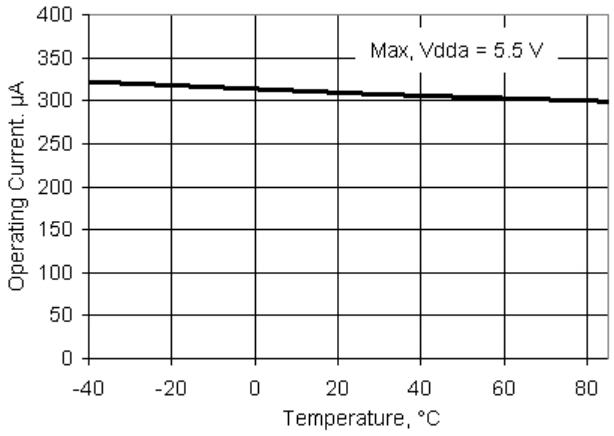


Figure 11-47. VDAC Operating Current vs Temperature, 1 V Mode, High speed mode



11.6 Digital Peripherals

Specifications are valid for –40 °C ≤ T_A ≤ 85 °C and T_J ≤ 100 °C, except where noted. Specifications are valid for 1.71 V to 5.5 V, except where noted.

11.6.1 Timer

The following specifications apply to the Timer/Counter/PWM peripheral in timer mode. Timers can also be implemented in UDBs; for more information, see the Timer component datasheet in PSoC Creator.

Table 11-33. Timer DC Specifications

Parameter	Description	Conditions	Min	Typ	Max	Units
	Block current consumption	16-bit timer, at listed input clock frequency	–	–	–	µA
	3 MHz		–	15	–	µA
	12 MHz		–	60	–	µA
	50 MHz		–	260	–	µA

Table 11-34. Timer AC Specifications

Parameter	Description	Conditions	Min	Typ	Max	Units
	Operating frequency		DC	–	50.01	MHz
	Capture pulse width (Internal)		21	–	–	ns
	Capture pulse width (external)		42	–	–	ns
	Timer resolution		21	–	–	ns
	Enable pulse width		21	–	–	ns
	Enable pulse width (external)		42	–	–	ns
	Reset pulse width		21	–	–	ns
	Reset pulse width (external)		42	–	–	ns

11.6.2 Counter

The following specifications apply to the Timer/Counter/PWM peripheral, in counter mode. Counters can also be implemented in UDBs; for more information, see the Counter component datasheet in PSoC Creator.

Table 11-35. Counter DC Specifications

Parameter	Description	Conditions	Min	Typ	Max	Units
	Block current consumption	16-bit counter, at listed input clock frequency	–	–	–	µA
	3 MHz		–	15	–	µA
	12 MHz		–	60	–	µA
	50 MHz		–	260	–	µA

Table 11-36. Counter AC Specifications

Parameter	Description	Conditions	Min	Typ	Max	Units
	Operating frequency		DC	–	50.01	MHz
	Capture pulse		21	–	–	ns
	Resolution		21	–	–	ns
	Pulse width		21	–	–	ns
	Pulse width (external)		42	–	–	ns
	Enable pulse width		21	–	–	ns
	Enable pulse width (external)		42	–	–	ns
	Reset pulse width		21	–	–	ns
	Reset pulse width (external)		42	–	–	ns

12. Ordering Information

In addition to the features listed in Table 12-1, every CY8C32 device includes: a precision on-chip voltage reference, precision oscillators, flash, ECC, DMA, a fixed function I²C, 4 KB trace RAM, JTAG/SWD programming and debug, external memory interface, and more. In addition to these features, the flexible UDBs and analog subsection support a wide range of peripherals. To assist you in selecting the ideal part, PSoC Creator makes a part recommendation after you choose the components required by your application. All CY8C32 derivatives incorporate device and flash security in user-selectable security levels; see the TRM for details.

Table 12-1. CY8C32 Family with Single Cycle 8051

Part Number	MCU Core				Analog								Digital				I/O[76]				Package	JTAG ID[77]
	CPU Speed (MHz)	Flash (KB)	SRAM (KB)	EEPROM (KB)	LCD Segment Drive	ADC	DAC	Comparator	SC/CT Analog Blocks	Opamps	DFB	CapSense	UDBs[75]	16-bit Timer/PWM	FS USB	CAN 2.0b	Total I/O	GPIO	SIO	USBIO		
16 KB Flash																						
CY8C3244AXI-153	50	16	2	0.5	✔	12-bit Del-Sig	1	2	0	0	–	✔	16	4	–	–	70	62	8	0	100-pin TQFP	0×1E099069
CY8C3244LTI-130	50	16	2	0.5	✔	12-bit Del-Sig	1	2	0	0	–	✔	16	4	–	–	46	38	8	0	68-pin QFN	0×1E082069
CY8C3244LTI-123	50	16	2	0.5	✔	12-bit Del-Sig	1	2	0	0	–	✔	16	4	–	–	29	25	4	0	48-pin QFN	0×1E07B069
CY8C3244PVI-133	50	16	2	0.5	✔	12-bit Del-Sig	1	2	0	0	–	✔	16	4	–	–	29	25	4	0	48-pin SSOP	0×1E085069
32 KB Flash																						
CY8C3245AXI-158	50	32	4	1	✔	12-bit Del-Sig	1	2	0	0	–	✔	20	4	–	–	70	62	8	0	100-pin TQFP	0×1E09E069
CY8C3245LTI-163	50	32	4	1	✔	12-bit Del-Sig	1	2	0	0	–	✔	20	4	–	–	46	38	8	0	68-pin QFN	0×1E0A3069
CY8C3245LTI-139	50	32	4	1	✔	12-bit Del-Sig	1	2	0	0	–	✔	20	4	–	–	29	25	4	0	48-pin QFN	0×1E08B069
CY8C3245PVI-134	50	32	4	1	✔	12-bit Del-Sig	1	2	0	0	–	✔	20	4	–	–	29	25	4	0	48-pin SSOP	0×1E086069
CY8C3245AXI-166	50	32	4	1	✔	12-bit Del-Sig	1	2	0	0	–	✔	20	4	✔	–	72	62	8	2	100-pin TQFP	0×1E0A6069
CY8C3245LTI-144	50	32	4	1	✔	12-bit Del-Sig	1	2	0	0	–	✔	20	4	✔	–	31	25	4	2	48-pin QFN	0×1E090069
CY8C3245PVI-150	50	32	4	1	✔	12-bit Del-Sig	1	2	0	0	–	✔	20	4	✔	–	31	25	4	2	48-pin SSOP	0×1E096069
CY8C3245FNI-212	50	32	4	1	✔	12-bit Del-Sig	1	2	0	0	–	✔	20	4	–	–	46	38	8	0	72-pin WLCSP	0x1E0D4069
64 KB Flash																						
CY8C3246LTI-149	50	64	8	2	✔	12-bit Del-Sig	1	2	0	0	–	✔	24	4	–	–	46	38	8	0	68-pin QFN	0×1E095069
CY8C3246PVI-147	50	64	8	2	✔	12-bit Del-Sig	1	2	0	0	–	✔	24	4	✔	–	31	25	4	2	48-pin SSOP	0×1E093069
CY8C3246AXI-131	50	64	8	2	✔	12-bit Del-Sig	1	2	0	0	–	✔	24	4	–	–	70	62	8	0	100-pin TQFP	0×1E083069
CY8C3246LTI-162	50	64	8	2	✔	12-bit Del-Sig	1	2	0	0	–	✔	24	4	–	–	29	25	4	0	48-pin QFN	0×1E0A2069
CY8C3246PVI-122	50	64	8	2	✔	12-bit Del-Sig	1	2	0	0	–	✔	24	4	–	–	29	25	4	0	48-pin SSOP	0×1E07A069
CY8C3246AXI-138	50	64	8	2	✔	12-bit Del-Sig	1	2	0	0	–	✔	24	4	✔	–	72	62	8	2	100-pin TQFP	0×1E08A069
CY8C3246LTI-128	50	64	8	2	✔	12-bit Del-Sig	1	2	0	0	–	✔	24	4	✔	–	48	38	8	2	68-pin QFN	0×1E080069
CY8C3246LTI-125	50	64	8	2	✔	12-bit Del-Sig	1	2	0	0	–	✔	24	4	✔	–	31	25	4	2	48-pin QFN	0×1E07D069
CY8C3246FNI-213	50	64	8	2	✔	12-bit Del-Sig	1	2	–	–	–	✔	24	4	–	–	46	38	8	–	72-pin WLCSP	0x1E0D5069

Notes

75. UDBs support a wide variety of functionality including SPI, LIN, UART, timer, counter, PWM, PRS, and others. Individual functions may use a fraction of a UDB or multiple UDBs. Multiple functions can share a single UDB. See the Example Peripherals on page 45 for more information on how UDBs can be used.
76. The I/O Count includes all types of digital I/O: GPIO, SIO, and the two USB I/O. See the I/O System and Routing on page 37 for details on the functionality of each of these types of I/O.
77. The JTAG ID has three major fields. The most significant nibble (left digit) is the version, followed by a 2 byte part number and a 3 nibble manufacturer ID.

Figure 13-1. 48-pin (300 mil) SSOP Package Outline

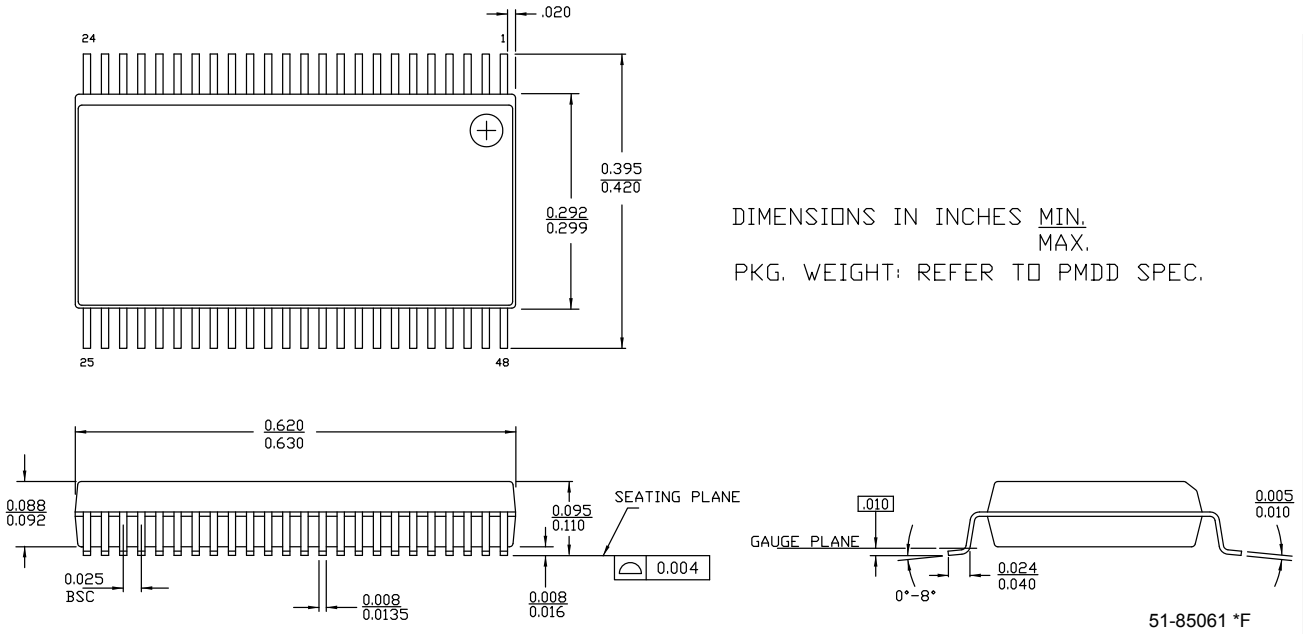
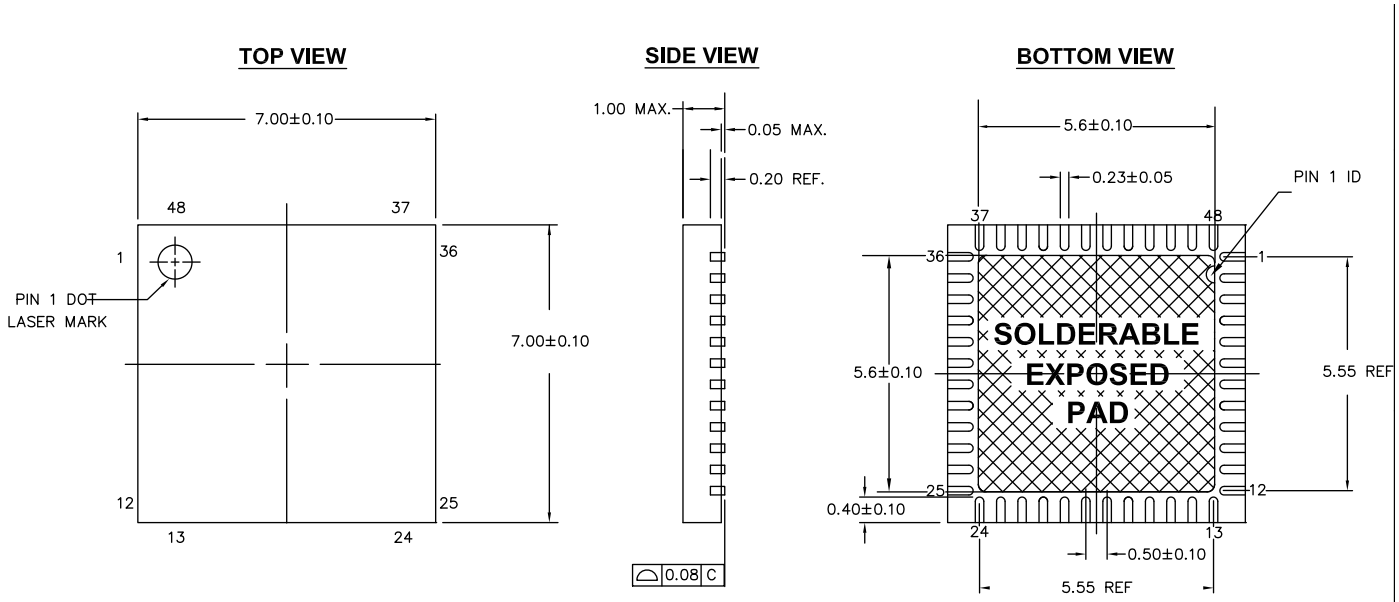


Figure 13-2. 48-pin QFN Package Outline



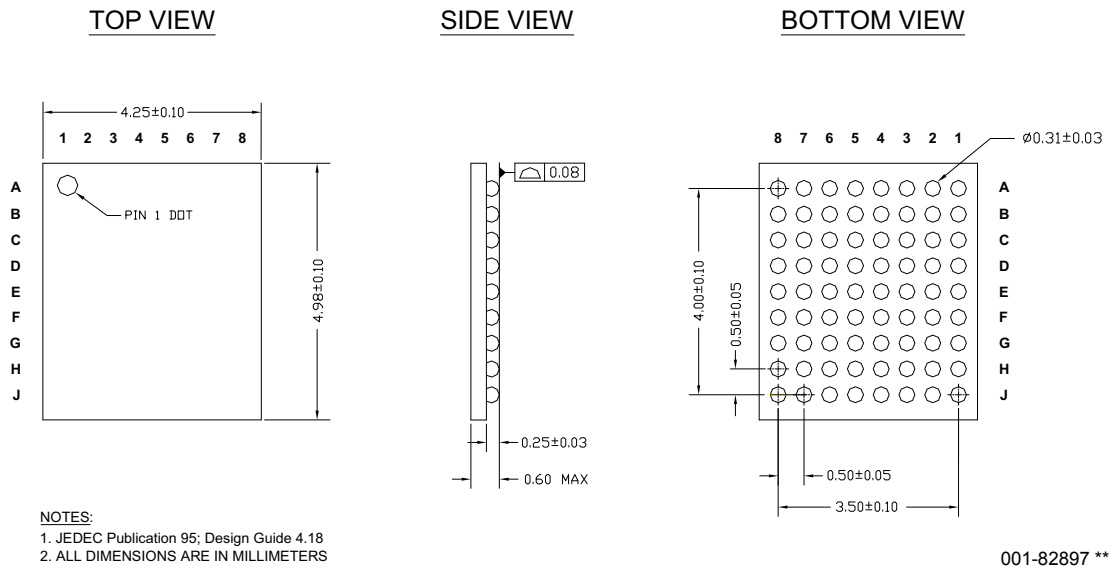
NOTES:

1. HATCH AREA IS SOLDERABLE EXPOSED METAL.
2. REFERENCE JEDEC#: MO-220
3. PACKAGE WEIGHT: REFER TO PMDD SPEC.
4. ALL DIMENSIONS ARE IN MM [MIN/MAX]
5. PACKAGE CODE

PART #	DESCRIPTION
LT48D	LEAD FREE

001-45616 *E

Figure 13-5. WLCSP Package (4.25 × 4.98 × 0.60 mm)



NOTES:
1. JEDEC Publication 95; Design Guide 4.18
2. ALL DIMENSIONS ARE IN MILLIMETERS

001-82897 **

Description Title: PSoC® 3: CY8C32 Family Data Sheet Programmable System-on-Chip (PSoC®) *(continued)* Document Number: 001-56955				
Revision	**ECN**	**Submission Date**	**Orig. of Change**	**Description of Change**
*X	4932879	09/24/2015	MKEA	Changed the Regulator Output Capacitor min and max from "-" to 0.9 and 1.1, respectively. Added reference to AN54439 in Section 11.9.3. Added MHz ECO DC specs table. Removed references to IPOR rearm issues in Section 6.3.1.1. Table 6-1: Changed DSI Fmax to 33 MHz. Figure 6-1: Changed External I/O or DSI to 0-33 MHz. Table 11-10: Changed Fgpioin Max to 33 MHz. Table 11-12: Changed Fsioin Max to 33 MHz.
*Y	5322536	06/27/2016	MKEA	Updated More Information. Corrected typos in External Electrical Connections. Added links to CAD Libraries in Section 2.